

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC070N10NS5	**Issued**	1. August 2018
MA#	MA002213760		
Package	PG-TDSON-8-7	**Weight***	118.52 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.848	0.72	0.72	7155	7155
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		319	
	non noble metal	copper	7440-50-8	37.762	31.86	31.90	318609	319024
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	379	379
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		731	
	plastics	epoxy resin	-	6.843	5.77		57734	
	inorganic material	silicondioxide	60676-86-0	36.379	30.69	36.53	306940	365405
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12248	12248
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1397	1397
solder	non noble metal	tin	7440-31-5	0.025	0.02		209	
	noble metal	silver	7440-22-4	0.031	0.03		261	
	non noble metal	lead	7439-92-1	1.180	1.00	1.05	9960	10430
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.55	9.56	95511	95636
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		188	
	non noble metal	copper	7440-50-8	22.292	18.81	18.84	188082	188326
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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